CLAIMS:

[Claim 1]

A resin molding device, configured to perform resin molding of a molding target by using a thermosetting resin, the resin molding device comprising:

a molding mold;

a mold-clamping mechanism configured to perform clamping of the molding mold; and

a temperature adjustment mechanism configured to adjust a temperature of the molding mold,

wherein the temperature adjustment mechanism is configured to heat the molding mold in a state where the clamping is completed during the resin molding, and to cool the molding mold while the state where the clamping is completed is maintained after the resin molding,

wherein the molding target includes a substrate on which at least one of electronic components is mounted on one surface, and the surface of the substrate on which at least one of the electronic components is mounted is sealed with the thermosetting resin.

[Claim 2]

The resin molding device according to claim 1, wherein the molding mold includes:

an upper mold configured to hold the molding target; and

a lower mold facing the upper mold and in which the resin used for the resin molding is arranged.

[Claim 3]

The resin molding device according to claim 1 or 2, wherein piping is arranged inside the molding mold, and

the temperature adjustment mechanism is configured to adjust the temperature of the molding mold by supplying a heat medium to the piping.

[Claim 4]

The resin molding device according to any one of claims 1 to 3, further comprising a transport mechanism configured to transport the molding target that has been molded with resin.

[Claim 5]

A method for manufacturing a resin molded article using the resin molding device according to any one of claims 1 to 4, the method comprising:

supplying the molding target to the molding mold;

performing the resin molding by performing clamping of the molding mold heated by the temperature adjustment mechanism, wherein the surface of the substrate on which at least one of the electronic components is mounted is sealed with the thermosetting resin; and

cooling the molding mold by the temperature adjustment mechanism while the state where the clamping is completed is maintained after the resin molding.